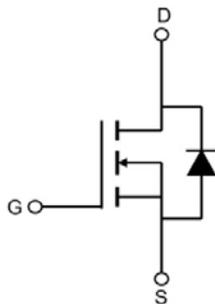
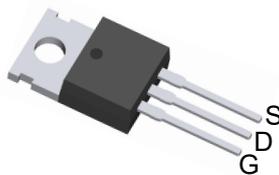


## SGT N-channel Power MOSFET

**MTR006N10CT**  
**TO-220CB**



$V_{DS}$	100	V
$R_{DS(on),TYP@ V_{GS}=10V}$	5.2	m $\Omega$
$I_D$	120	A

### Features

- 1、 Low on – resistance
- 2、 Package TO-220CB
- 3、 SGT N-channel Power MOSFET

### Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

**Maximum ratings, at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Symbol	Parameter	Rating	Unit	
V(BR)DSS	Drain-Source breakdown voltage	100	V	
VGS	Gate-Source voltage	$\pm 20$	V	
ID	Continuous drain current @VGS=10V	$T_C = 25^\circ\text{C}$	120	A
		$T_C = 100^\circ\text{C}$	75	A
IDM	Pulse drain current tested	$T_C = 25^\circ\text{C}$	345	A
EAS	Avalanche energy, single pulsed	130	mJ	
IAS	Avalanche Current	51	A	
PD	Maximum power dissipation	$T_C = 25^\circ\text{C}$	208	W
		$T_C = 100^\circ\text{C}$	83	W
TSTG,TJ	Storage and Junction Temperature Range	-55 to 150	$^\circ\text{C}$	

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
R $\theta$ JA	Thermal Resistance, Junction-to-Ambient	45	°C/W
R $\theta$ JC	Thermal Resistance, Junction-to-Case	0.6	°C/W

## Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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### Static Electrical Characteristics @ T<sub>j</sub>=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	108	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	5.2	6.0	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	--	81	--	S

### Dynamic Electrical Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V , f=1MHz	--	2369	--	pF
C <sub>oss</sub>	Output Capacitance		--	545	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	11.6	--	pF
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V , f=1MHz	--	2.0	--	Ω
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>DS</sub> =50V, I <sub>D</sub> =20A , V <sub>GS</sub> =10V	--	38	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	7.9	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	9.2	--	nC

## Switching Characteristics

Td(on)	Turn-on Delay Time	V <sub>DS</sub> =50V, R <sub>g</sub> =6.0Ω, V <sub>GS</sub> =10V, R <sub>L</sub> =2.5Ω	--	12.6	--	ns
Tr	Turn-on Rise Time		--	29	--	ns
Td(off)	Turn-Off Delay Time		--	40	--	ns
Tf	Turn-Off Fall Time		--	44	--	ns

## Source- Drain Diode Characteristics@ T<sub>j</sub> = 25°C (unless otherwise stated)

I <sub>s</sub>	Diode Forward Current		--	--	160	A
V <sub>SD</sub>	Forward on voltage	V <sub>GS</sub> =0V, I <sub>s</sub> =1A	--	0.7	1.0	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A/μs	--	60	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	110	--	nC

### NOTE:

1. Computed continuous current assumes the condition of T<sub>J\_Max</sub> while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under T<sub>J\_Max</sub> = 150°C.
3. This single-pulse measurement was taken under the following condition [L = 100μH, V<sub>GS</sub> = 10V, V<sub>DS</sub> = 50V] while its value is limited by T<sub>J\_Max</sub> = 150°C.
4. The power dissipation PD is based on T<sub>J\_Max</sub> = 150°C.
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

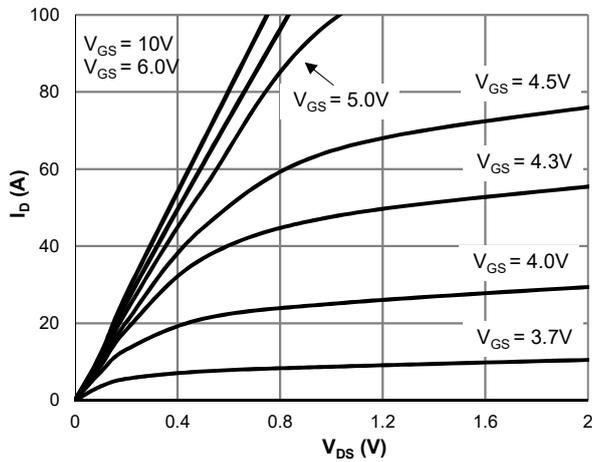


Figure 1: Saturation Characteristics

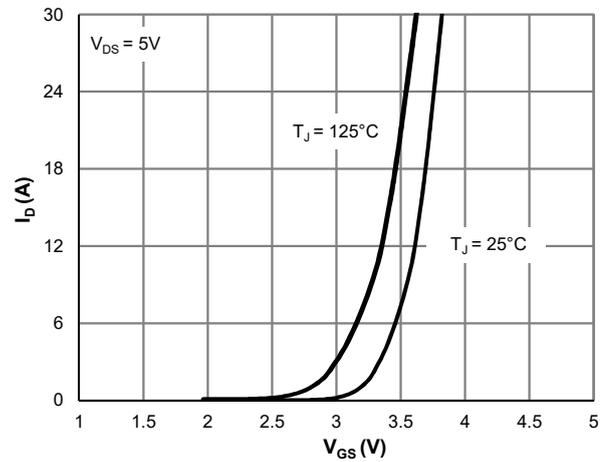


Figure 2: Transfer Characteristics

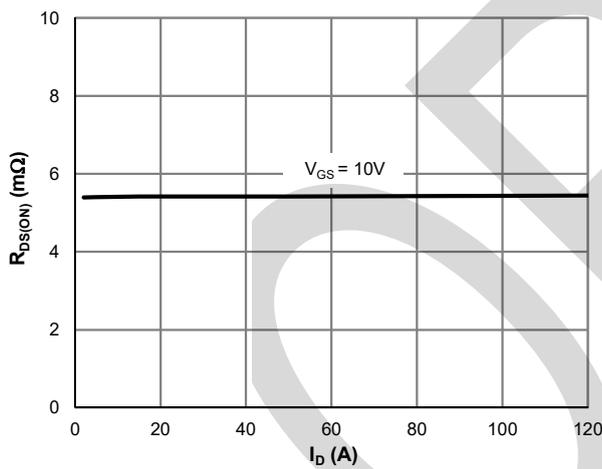


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

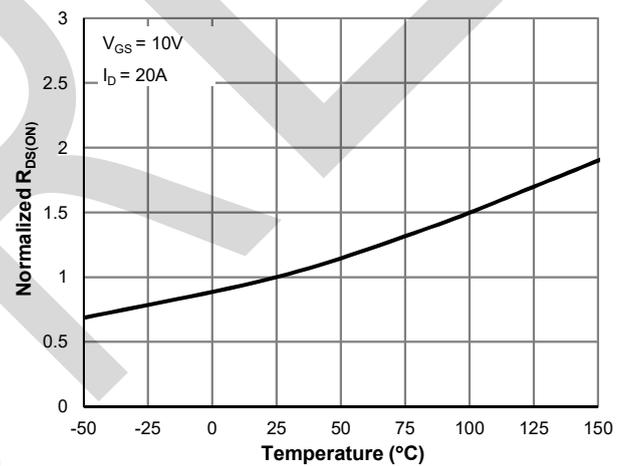


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

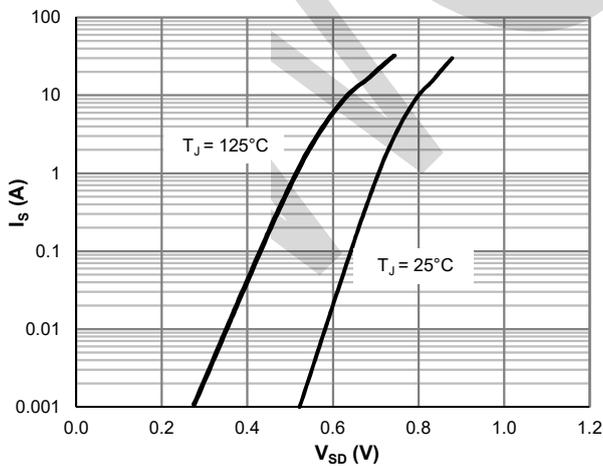


Figure 5: Body-Diode Characteristics

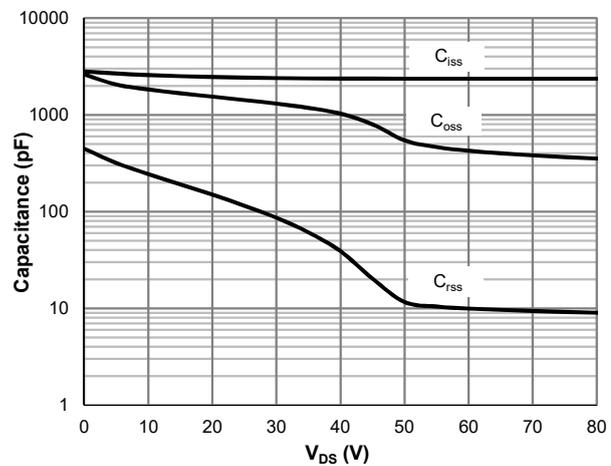


Figure 6: Capacitance Characteristics

## Typical Characteristics

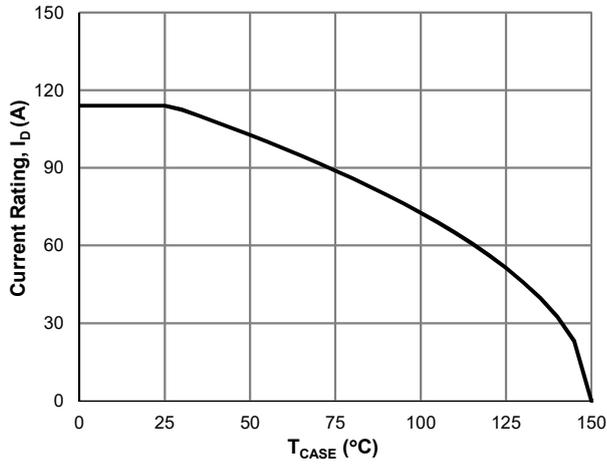


Figure 7: Current De-rating

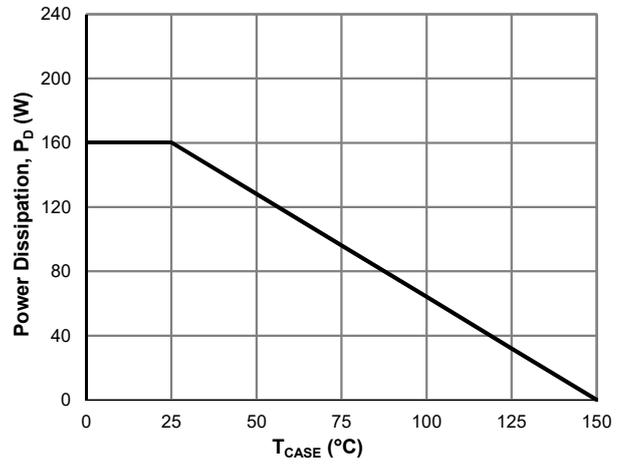


Figure 8: Power De-rating

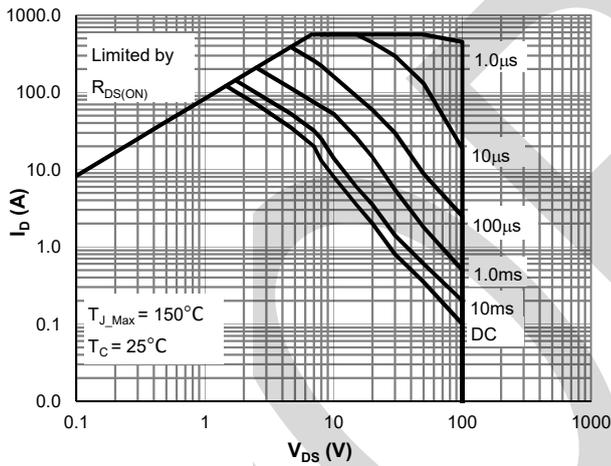


Figure 9: Maximum Safe Operating Area

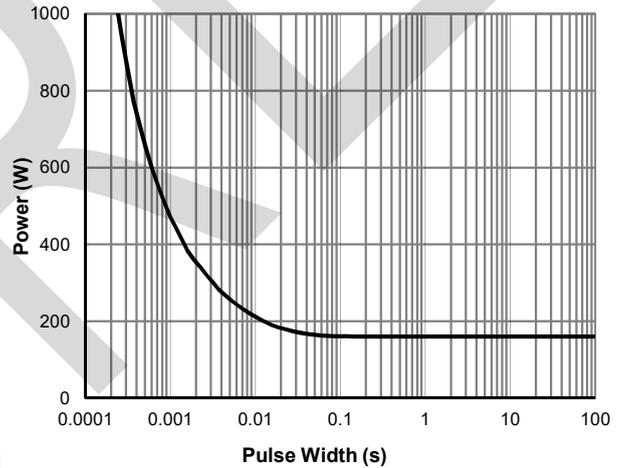


Figure 10: Single Pulse Power Rating, Junction-to-Case

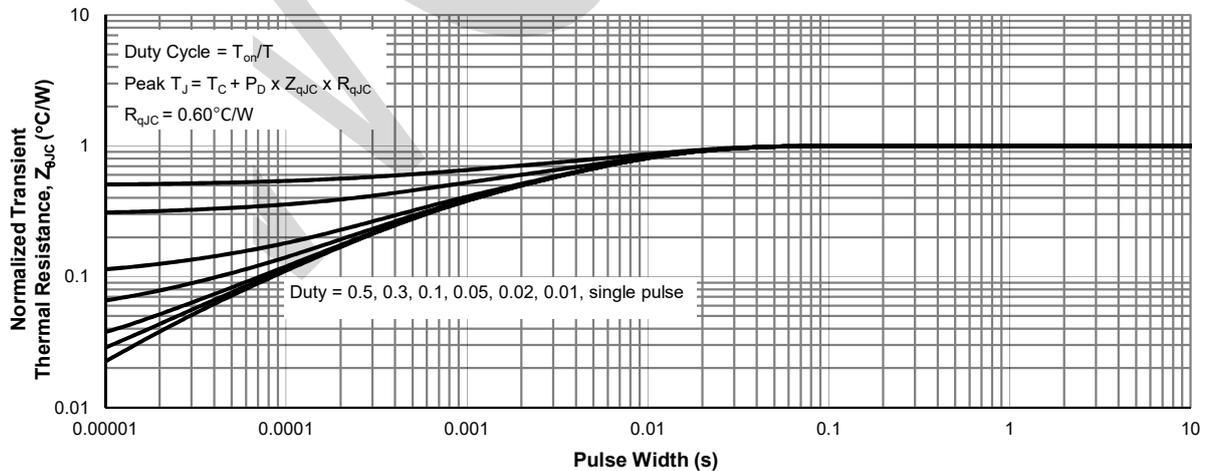
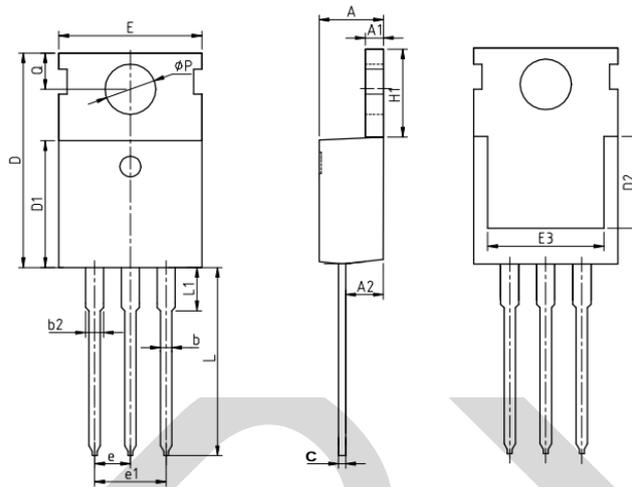


Figure 11: Normalized Maximum Transient Thermal Impedance

## PACKAGE OUTLINE DIMENSIONS

Note:unit mm

### TO-220CB



### COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.25	1.30	1.45
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.40	0.50	0.65
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50		
E	9.70	10.00	10.30
E3	7.00		
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1		3.10	3.40
ΦP	3.40	3.60	3.80
Q	2.60	2.80	3.00